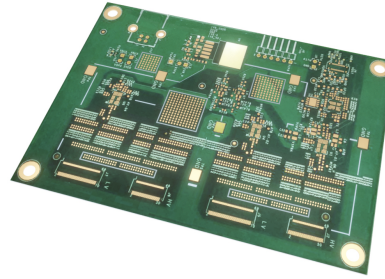


We are constantly innovating



Features	Standard	Advanced
Number Of Layers	1+N+1, 2N+2, 3+N+3	4+N+4
Base Material	FR-4	FR-5
Maximum Panel Size	518mm x 412mm	620mm x 468mm
Minimum Board Thickness	0.5mm	0.35mm
Maximum Micro-via in Pad	0.10mm	0.15mm
Aspect for Micro-via	0.8:1	1:1
Maximum Copper Thickness	Inner Layer: 0.5oz Outer Layer: 1.0oz	Inner Layer: 2.0oz Outer Layer: 3.0oz
Surface Finishing	Electroless Nickel Immersion Gold (ENIG)	Immersion Tin, Immersion Silver, Organic Solderability Preservative (OSP)